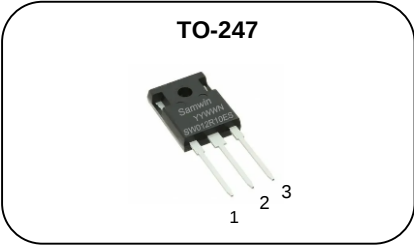


N-channel Enhanced mode TO-247 MOSFET

Features

- High ruggedness
- Low $R_{DS(ON)}$ (Typ 1.8mΩ)@ $V_{GS}=10V$
- Low Gate Charge (Typ 207nC)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Application:Synchronous Rectification, Li Battery Protect Board, Motor Drives



1. Gate 2.Drain 3.Source

$BV_{DSS} : 100V$
 $I_D : 320A$
 $R_{DS(ON)} : 1.8m\Omega$

General Description

This power MOSFET is produced with advanced technology of SAMWIN. This technology enable the power MOSFET to have better characteristics, including fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics.



Order Codes

Item	Sales Type	Marking	Package	Packaging
1	SW T 012R10ES	SW012R10ES	TO-247	TUBE

Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DSS}	Drain to source voltage	100	V
I_D	Continuous drain current (@ $T_C=25^{\circ}C$)	320*	A
	Continuous drain current (@ $T_C=100^{\circ}C$)	308*	A
I_{DM}	Drain current pulsed (note 1)	1280	A
V_{GS}	Gate to source voltage	± 20	V
E_{AS}	Single pulsed avalanche energy (note 2)	1936	mJ
E_{AR}	Repetitive avalanche energy (note 1)	190	mJ
dv/dt	Peak diode recovery dv/dt (note 3)	5	V/ns
P_D	Total power dissipation (@ $T_C=25^{\circ}C$)	735.3	W
	Derating factor above 25°C	5.9	W/°C
T_{STG}, T_J	Operating junction temperature & storage temperature	-55 ~ + 150	°C
T_L	Maximum lead temperature for soldering purpose, 1/8 from case for 5 seconds.	300	°C

*, Drain current is limited by junction temperature.

Thermal characteristics

Symbol	Parameter	Value	Unit
R_{thjc}	Thermal resistance, Junction to case	0.17	°C/W
R_{thja}	Thermal resistance, Junction to ambient	31	°C/W

Electrical characteristic (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Off characteristics						
BV _{DSS}	Drain to source breakdown voltage	V _{GS} =0V, I _D =250μA	100			V
ΔBV _{DSS} / ΔT _J	Breakdown voltage temperature coefficient	I _D =250μA, referenced to 25°C		0.05		V/°C
I _{DSS}	Drain to source leakage current	V _{DS} =100V, V _{GS} =0V			1	μA
		V _{DS} =80V, T _J =125°C			50	μA
I _{GSS}	Gate to source leakage current, forward	V _{GS} =20V, V _{DS} =0V			100	nA
	Gate to source leakage current, reverse	V _{GS} =-20V, V _{DS} =0V			-100	nA
On characteristics						
V _{GS(TH)}	Gate threshold voltage	V _{DS} =V _{GS} , I _D =250μA	2		4	V
R _{DS(ON)}	Drain to source on state resistance	V _{GS} =10V, I _D =30A, T _J =25°C		1.8	2.4	mΩ
		V _{GS} =10V, I _D =30A, T _J =125°C		2.8		mΩ
G _{fs}	Forward transconductance	V _{DS} =5V, I _D =20A		82		S
Dynamic characteristics						
C _{iss}	Input capacitance	V _{GS} =0V, V _{DS} =50V, f=100kHz		14426		pF
C _{oss}	Output capacitance			2040		
C _{rss}	Reverse transfer capacitance			31		
t _{d(on)}	Turn on delay time	V _{DS} =50V, I _D =30A, R _G =4.7Ω, V _{GS} =10V (note 4,5)		70		ns
t _r	Rising time			79		
t _{d(off)}	Turn off delay time			166		
t _f	Fall time			86		
Q _g	Total gate charge	V _{DS} =80V, V _{GS} =10V, I _D =30A , I _G =10mA (note 4,5)		207		nC
Q _{gs}	Gate-source charge			67		
Q _{gd}	Gate-drain charge			41		
R _g	Gate resistance	F=1MHz		2.9		Ω

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I _S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			320	A
I _{SM}	Pulsed source current				1280	A
V _{SD}	Diode forward voltage drop.	I _S =50A, V _{GS} =0V			1.4	V
t _{rr}	Reverse recovery time	I _S =30A, V _{GS} =0V, di _F /dt=100A/μs		101		ns
Q _{rr}	Reverse recovery charge			271		nC

- ※. Notes
1.

Repeative rating : pulse width limited by junction temperature.
2.

L =0.5mH, I_{AS} =88A, V_{DD}=50V, R_G=25Ω, Starting T_J = 25°C
3.

I_{SD} ≤30A, di/dt = 100A/μs, V_{DD} ≤ BV_{DSS}, Staring T_J =25°C
4.

Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%.
5.

Essentially independent of operating temperature.

Fig. 1. On-state characteristics

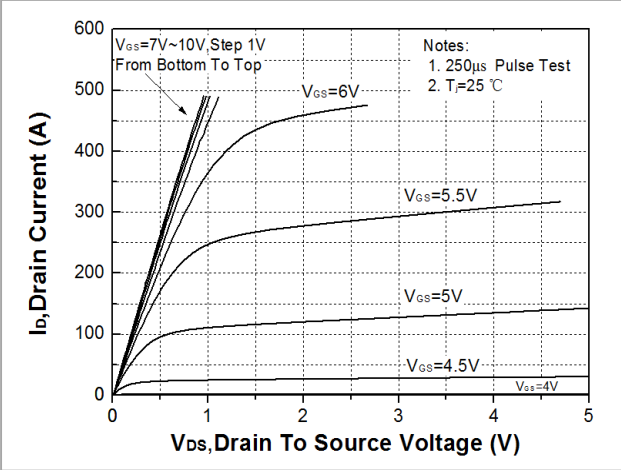


Fig. 2. Transfer Characteristics

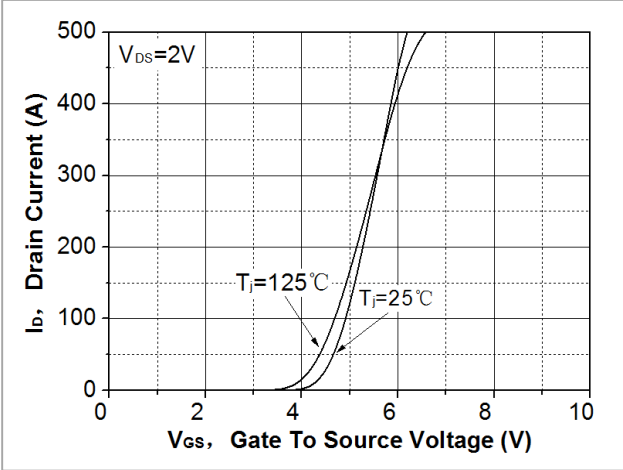


Fig. 3. On-resistance variation vs. drain current and gate voltage

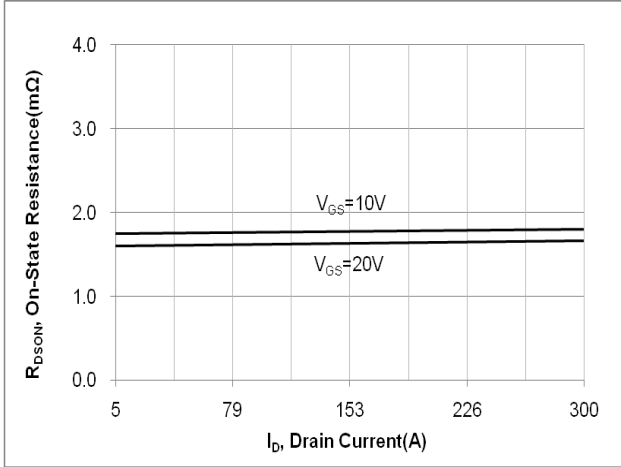


Fig. 4. On-state current vs. diode forward voltage

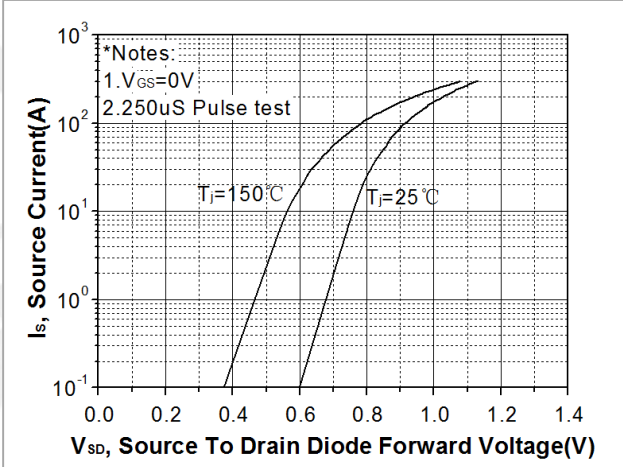


Fig 5. Breakdown voltage variation vs. junction temperature

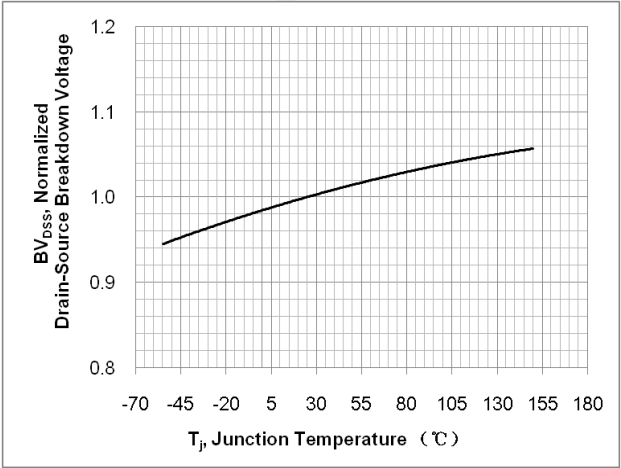


Fig. 6. On-resistance variation vs. junction temperature

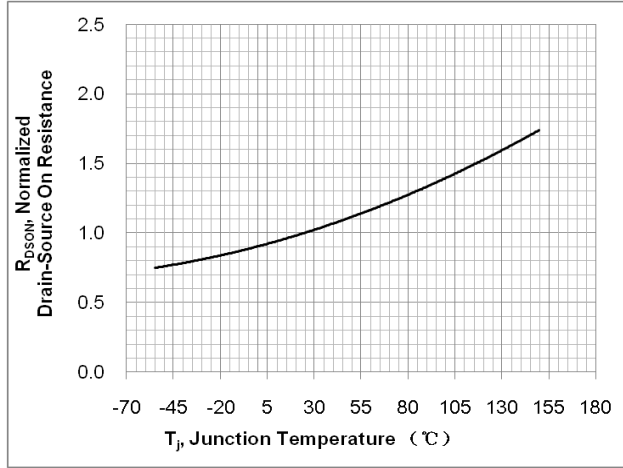


Fig. 7. Gate charge characteristics

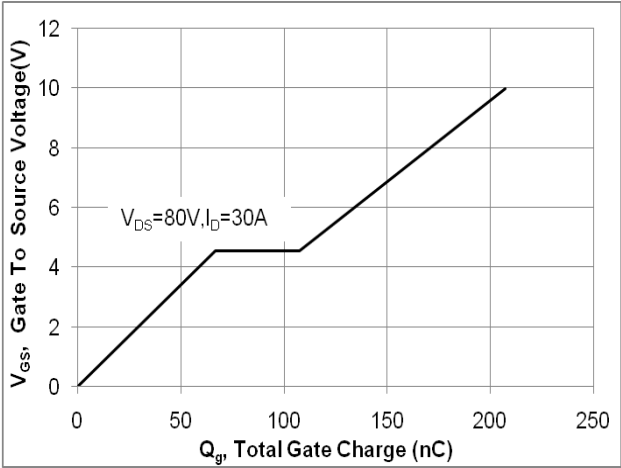


Fig. 8. Capacitance Characteristics

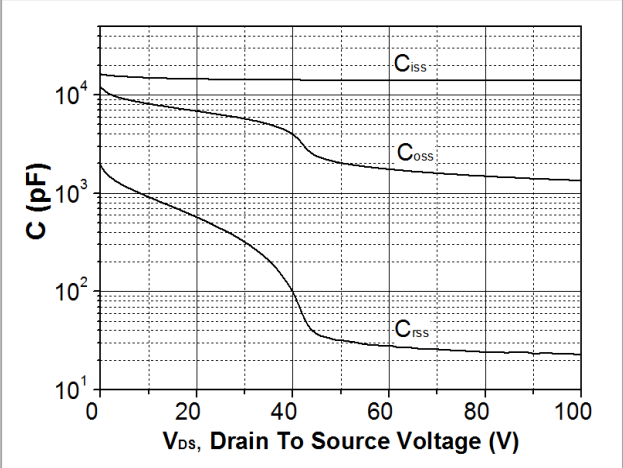


Fig. 9. Maximum safe operating area

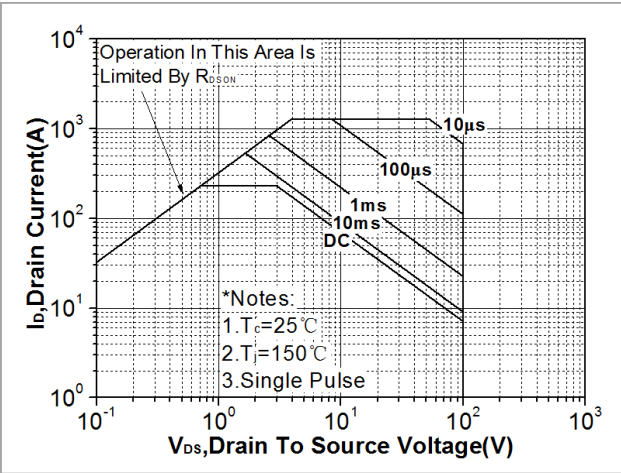


Fig. 10. Maximum drain current vs. case temperature

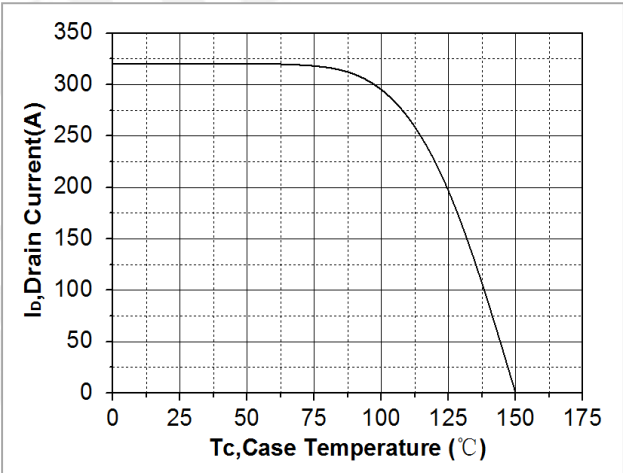


Fig. 11. Transient thermal response curve

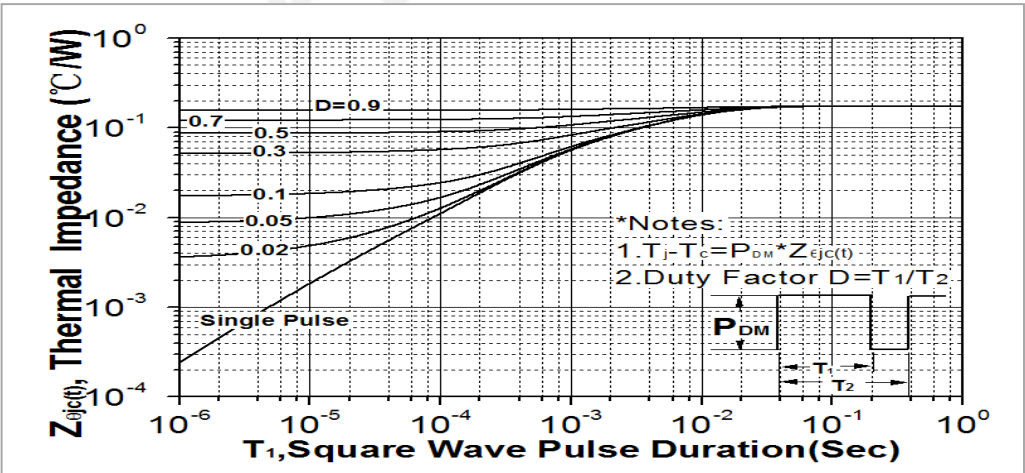


Fig. 12. Gate charge test circuit & waveform

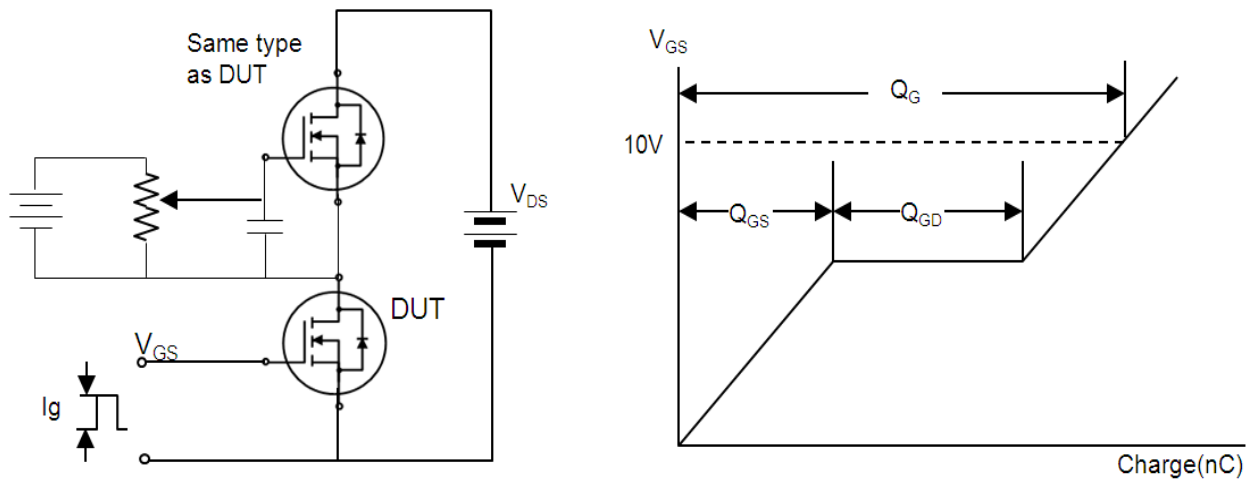


Fig. 13. Switching time test circuit & waveform

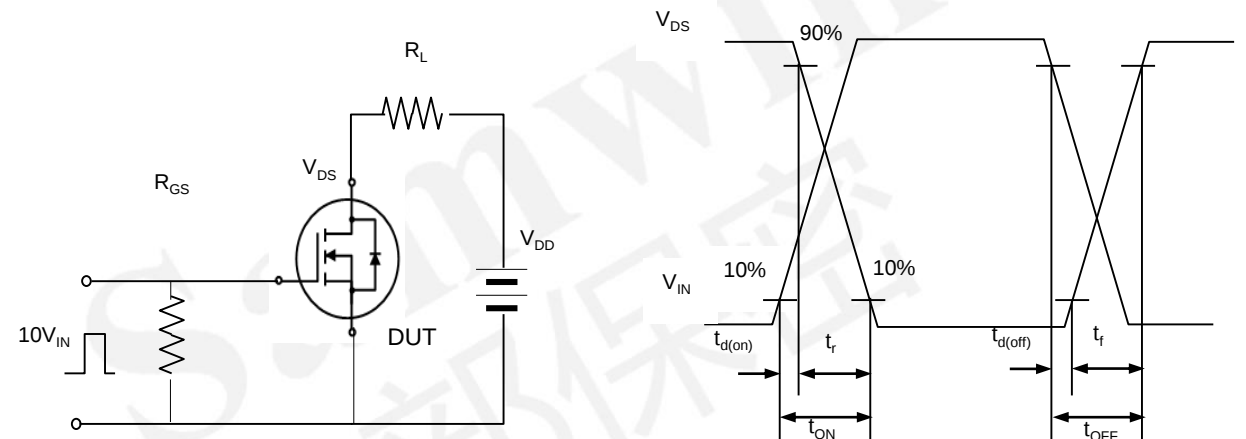


Fig. 14. Unclamped Inductive switching test circuit & waveform

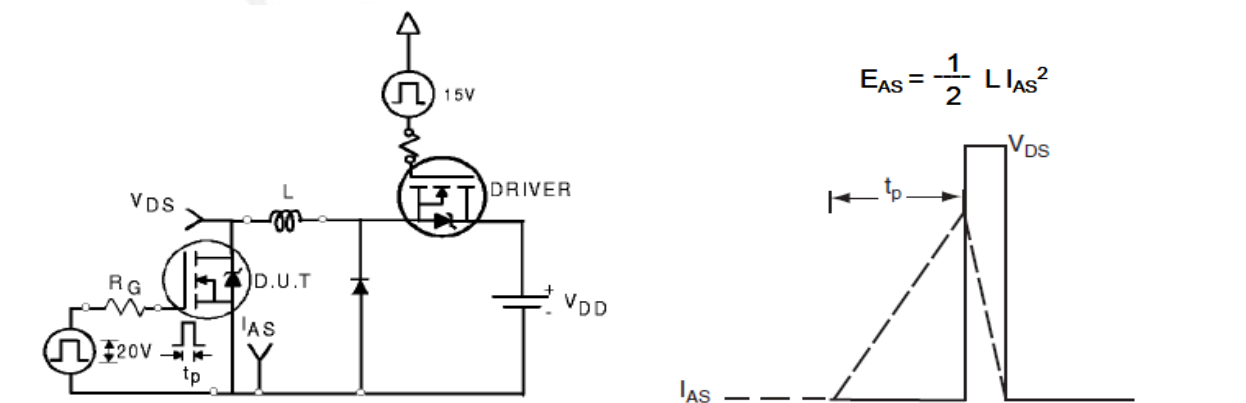
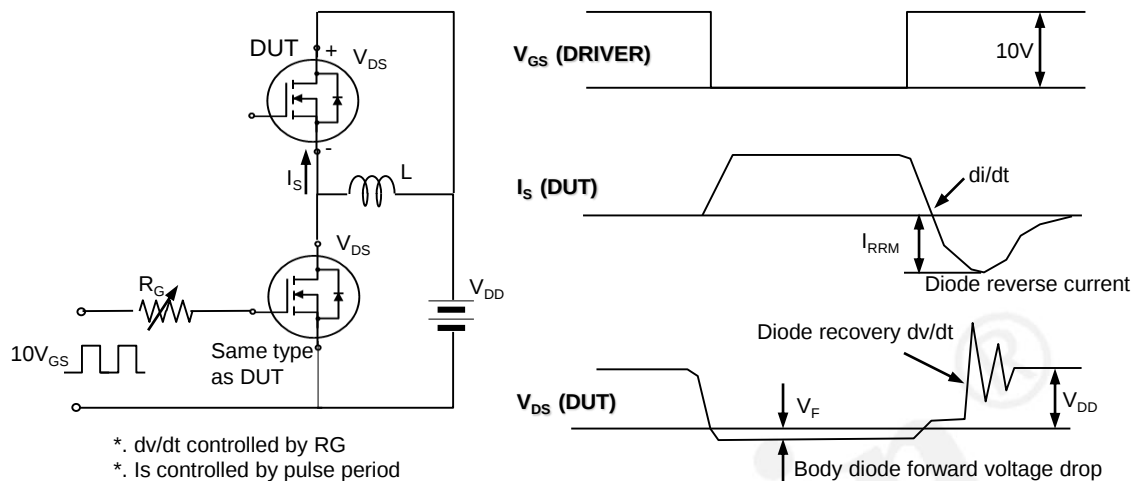


Fig. 15. Peak diode recovery dv/dt test circuit & waveform



DISCLAIMER

* All the data & curve in this document was tested in SEMIPOWER TESTING & APPLICATION CENTER.

* This product has passed the PCT,TC,HTRB,HTGB,HAST,PC and Solderdunk reliability testing.

* Qualification standards can also be found on the Web site (<http://www.semipower.com.cn>) 

* Suggestions for improvement are appreciated, Please send your suggestions to samwin@samwinsemi.com